



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

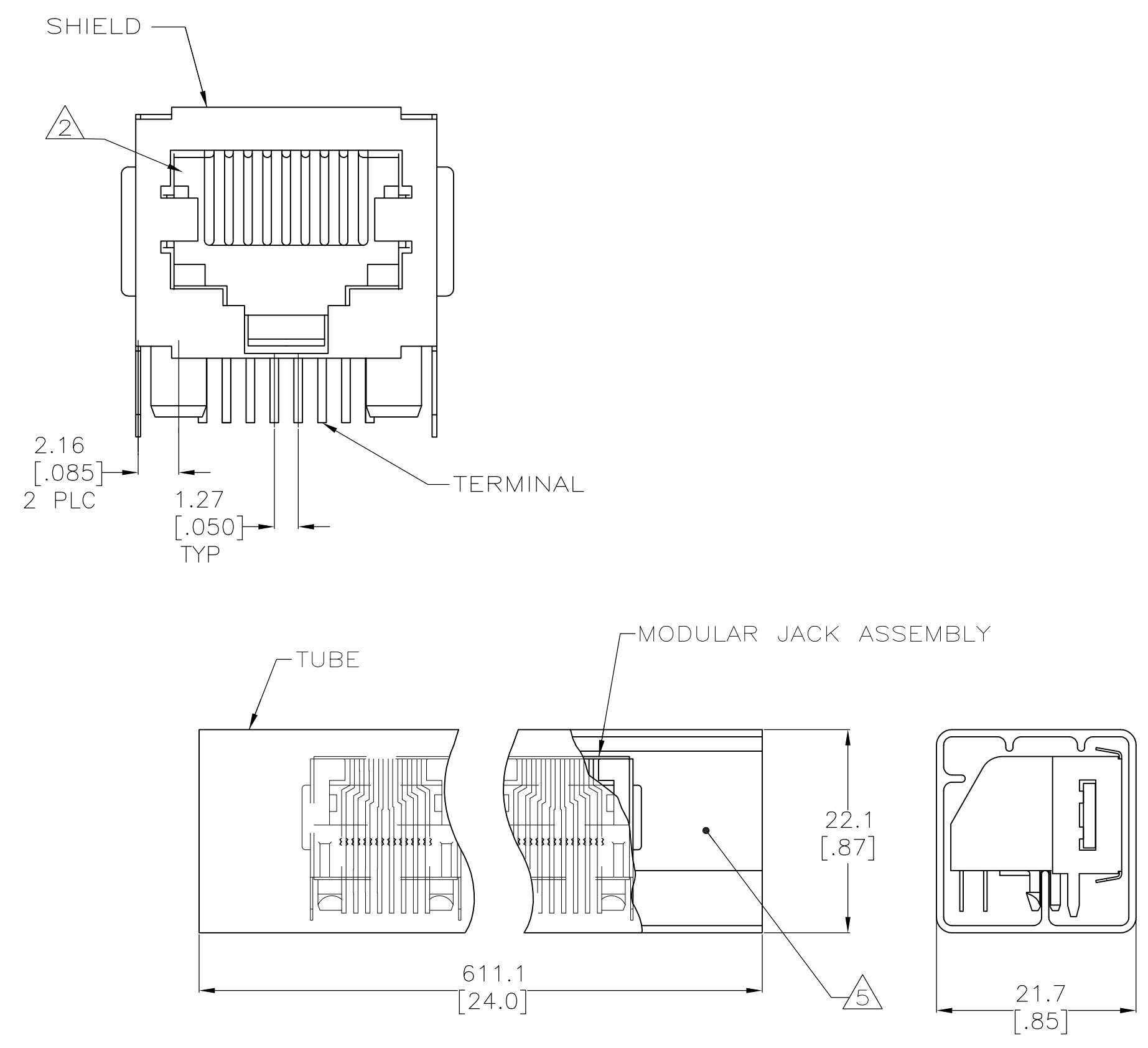
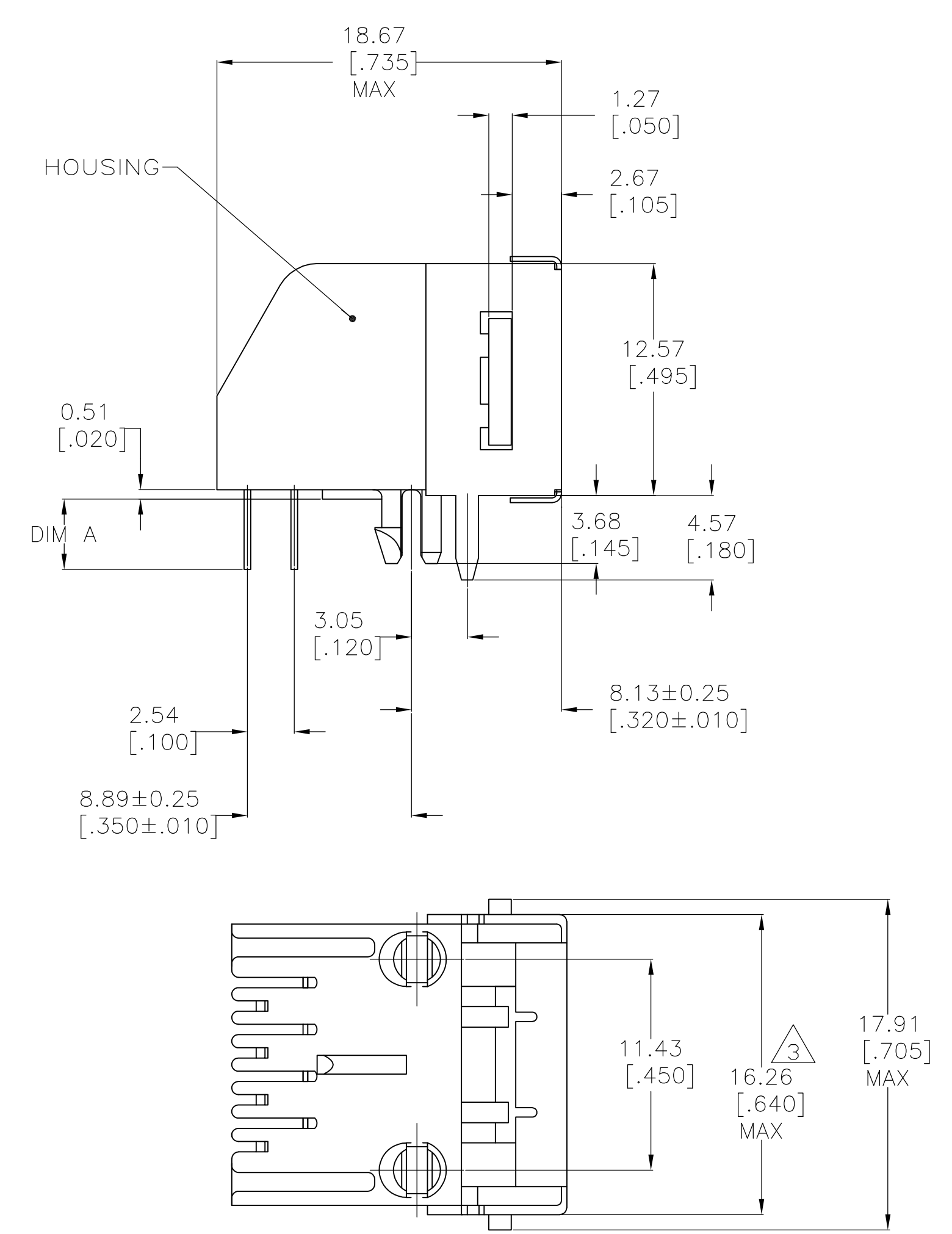
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

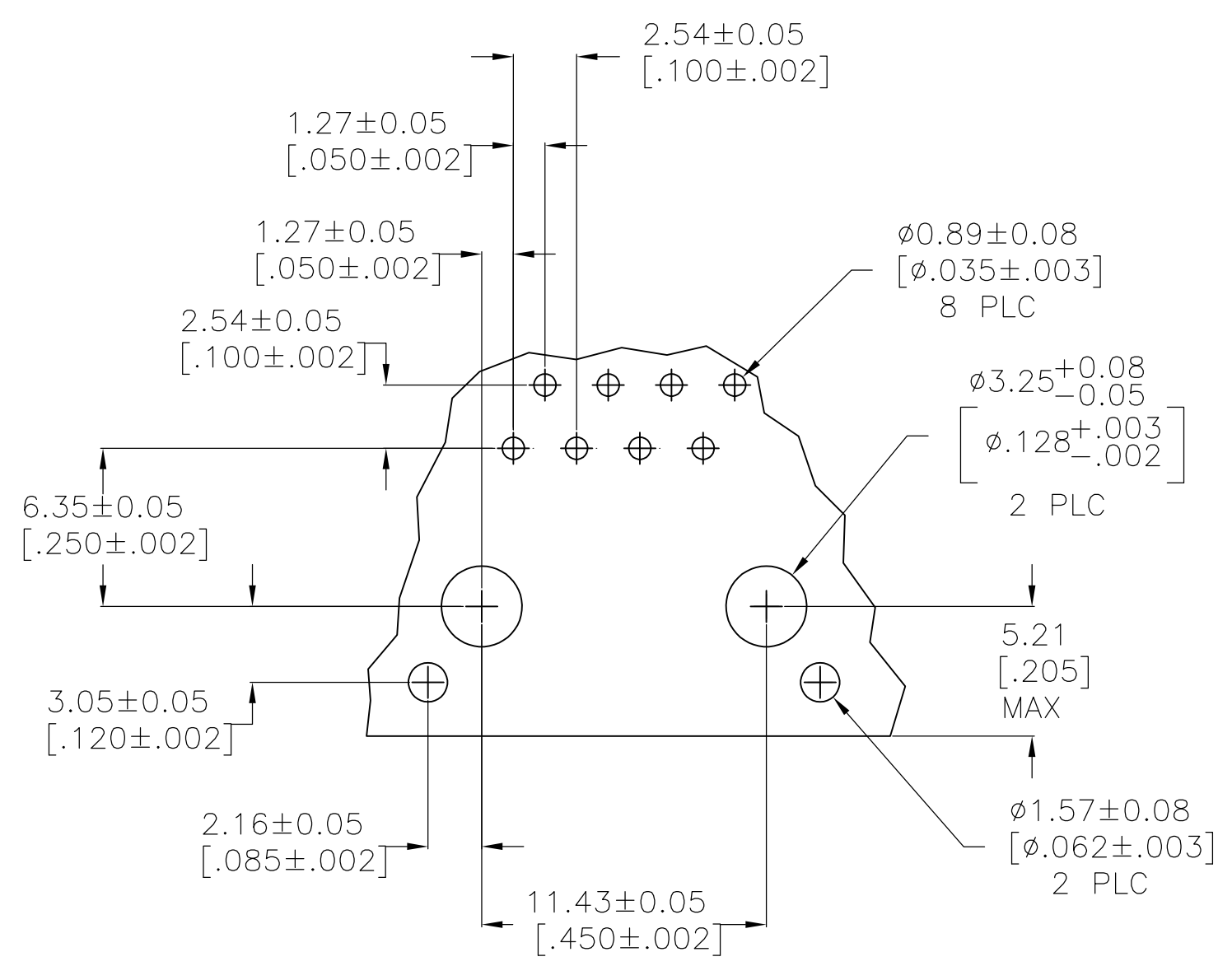
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



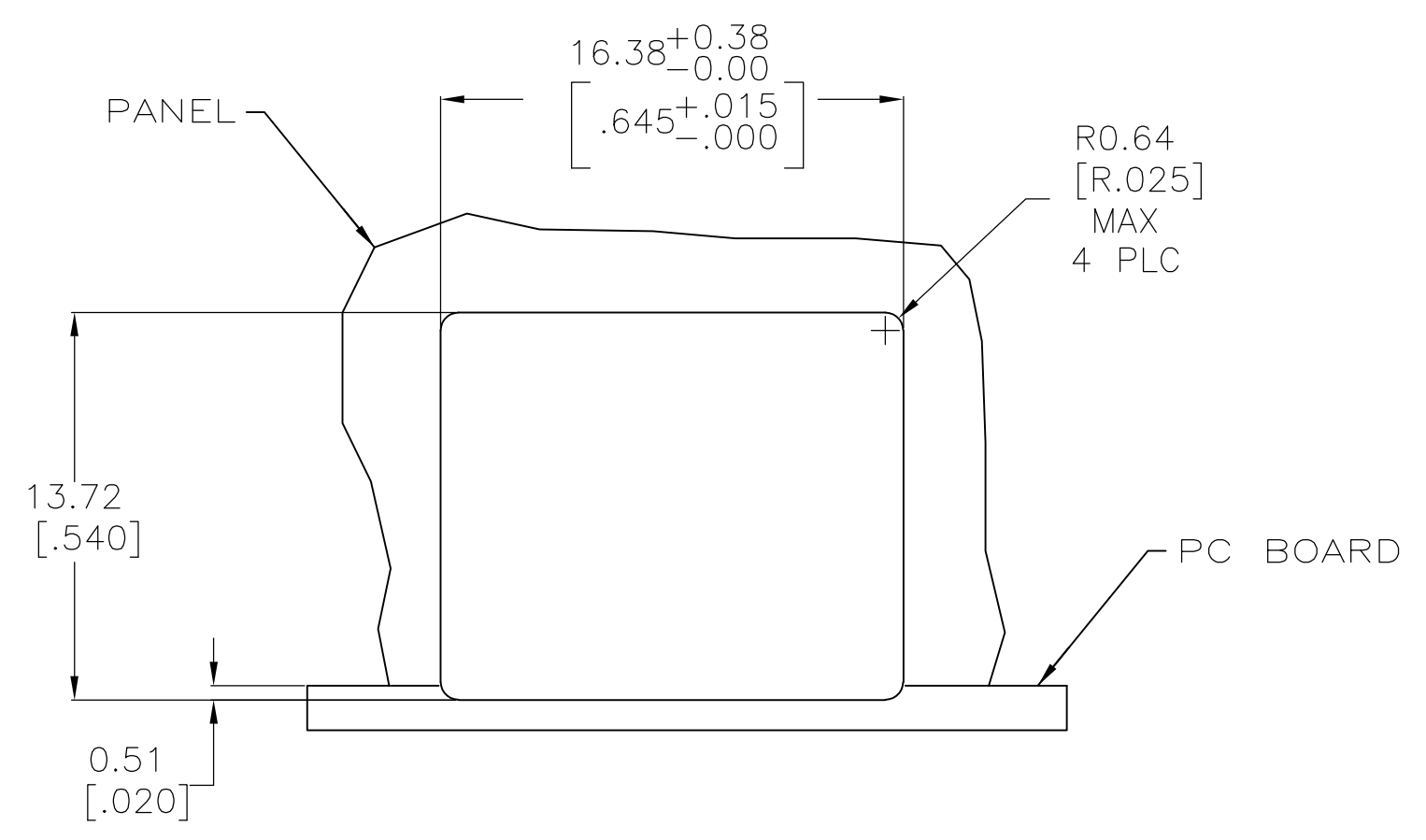
LOC		DIST		REVISIONS			
GP	00	P	LTR	DESCRIPTION	DATE	DMN	APVD
		D1		REVISED PER ECO-11-005140	28MAR11	RK	HMR



DETAIL B
SCALE 2:1



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT
(COMPONENT SIDE)



RECOMMENDED PANEL CUTOUT

1. MATERIAL:
 HOUSING - PBT POLYESTER, COLOR: BLACK
 TERMINAL - 0.36[.014] THICK PHOS BRONZE PLATED WITH 1.27 μ m [.000050] THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 2.03 μ m [.000080] THICK MATTE TIN IN SOLDER AREA OVER 1.27 μ m [.000050] THICK NICKEL UNDERPLATE
 SHIELD - 0.25 [.010] THICK COPPER ALLOY PLATED WITH 3.0 μ m [.000120] MINIMUM THICK REFLOWED TIN
- △2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
 - △3 DIMENSIONS MEASURED ALONG FRONT EDGES OF MATING FACE
 - △4 BULK PACKAGED IN A TRAY
 - △5 32 ASSEMBLIES PACKAGED PER TUBE. SEE DETAIL B

1.78-2.79 [.09±.02]	△4	5555153-6
2.54-3.05 [.11±.01]	△4	5555153-5
3.30-4.32 [.15±.02]	△5	5555153-3
3.30-4.32 [.15±.02]	△4	5555153-1
DIM A	PACKAGED	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± - 1 PLC ± - 2 PLC ± 0.13[.005] 3 PLC ± - 4 PLC ± - ANGLES ± -	APVD S. FLICKINGER	DATE 05NOV2007	NAME MODULAR JACK ASSEMBLY, SHIELDED, 8 POSITION, LOW PROFILE, RIGHT ANGLE, PANEL GROUND WITH PANEL STOPS
MATERIAL SEE NOTE 1	FINISH SEE NOTE 1	WEIGHT -	SIZE A1	RESTRICTED TO

STE TE Connectivity

CUSTOMER DRAWING SCALE 4:1 SHEET 1 OF 1 REV D1